

**描述 / Descriptions**

SOD-323 塑封封装 肖特基二极管。  
Schottky Diode in a SOD-323 Plastic Package.

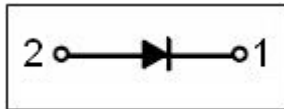
**特征 / Features**

金属硅结，多数载流子传导。过电压保护装置。低功率，高效率。大电流能力。低正向压降。高浪涌能力。用于低压高频逆变器，自由转动和极性保护应用。无卤产品。  
Metal silicon junction, majority carrier conduction. Guarding for overvoltage protection. Low power loss, high efficiency. High current capability. low forward voltage drop. High surge capability. For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications. HF Product.

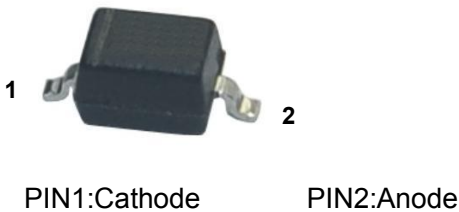
**用途 / Applications**

肖特基二极管。  
Schottky diode.

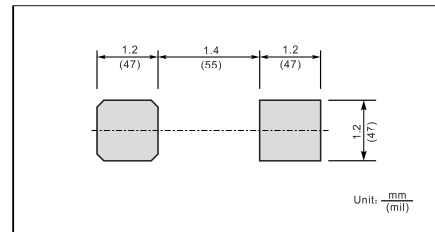
**内部等效电路 / Equivalent Circuit**



**引脚排列 / Pinning**



The recommended mounting pad size



**放大及印章代码 / h<sub>FE</sub> Classifications & Marking**

Model	RB551V-30
Marking	D

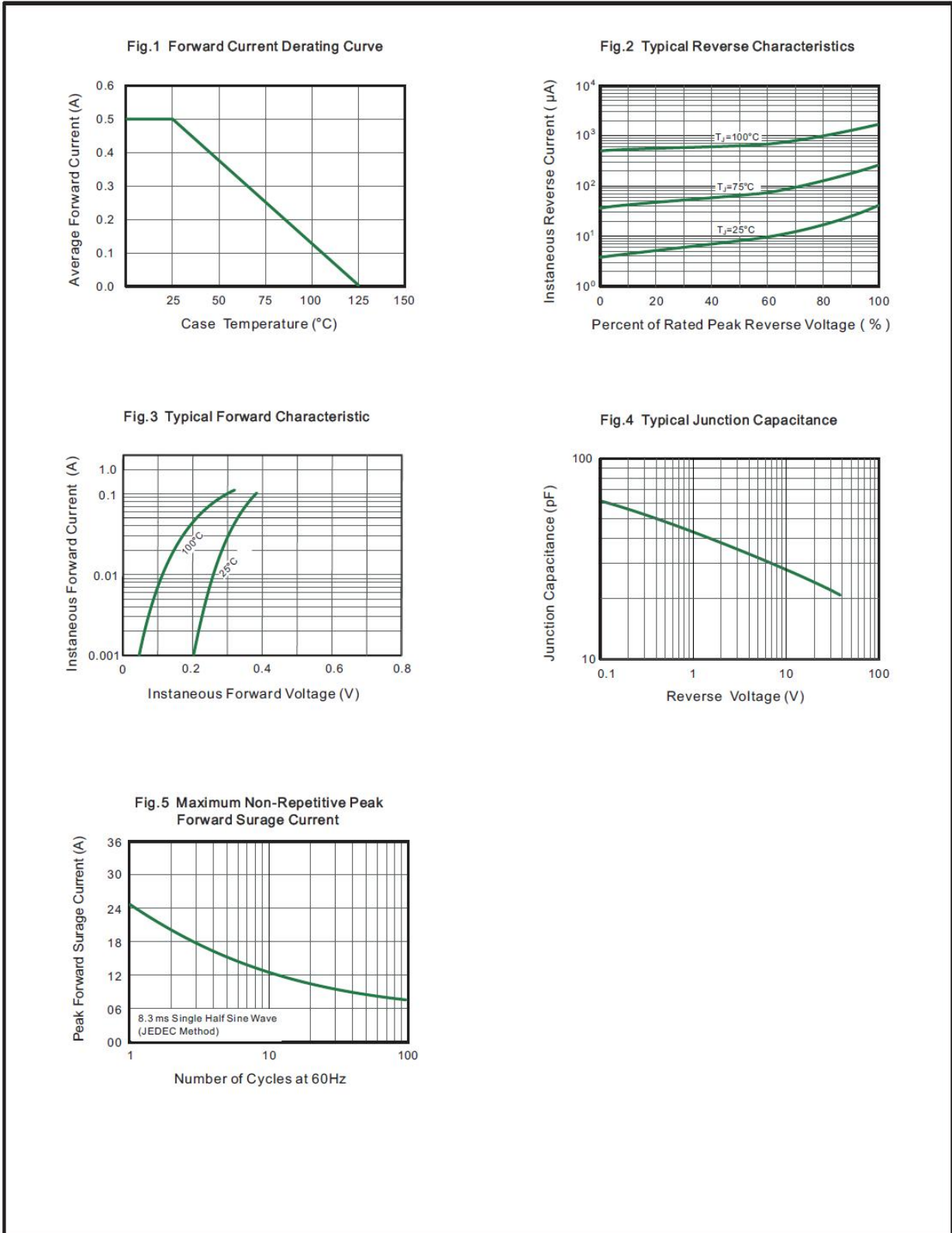
**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	30	V
DC reverse voltage	$V_R$	30	V
Maximum Average Forward Current at Ta=25°C	$I_O$	0.5	A
Peak Forward Surge Current, 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	$I_{FSM}$	25	A
Power dissipation	$P_d$	200	mW
Junction Temperature	$T_j$	-55 ~ +150	°C
Storage Temperature	$T_{stg}$	-55 ~ +150	°C

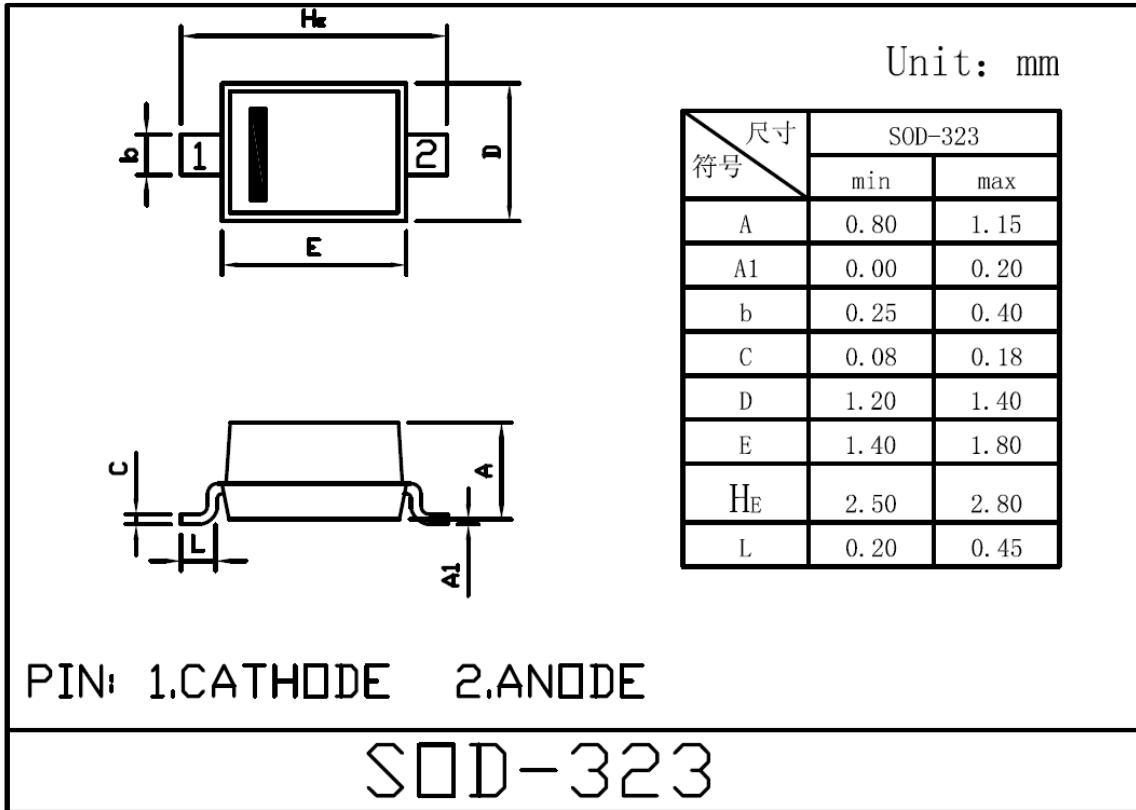
**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Maximum Instantaneous Forward Voltage	$V_F$	$I_F=100mA$	0.36	V
		$I_F=500mA$	0.47	
Maximum DC Reverse Current at Rated DC Blocking Voltage	$I_R$	$V_R=20$	100	uA

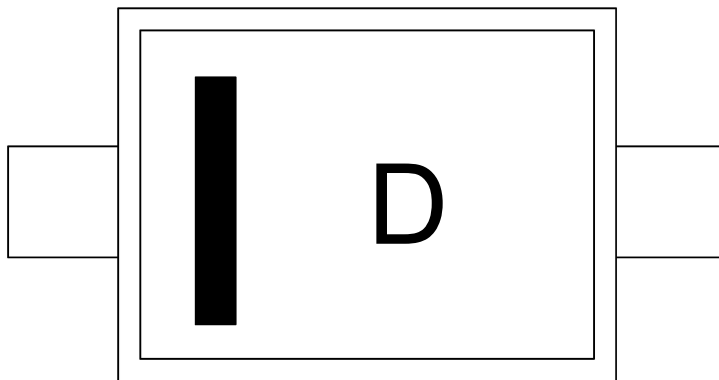
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions



印章说明 / Marking Instructions



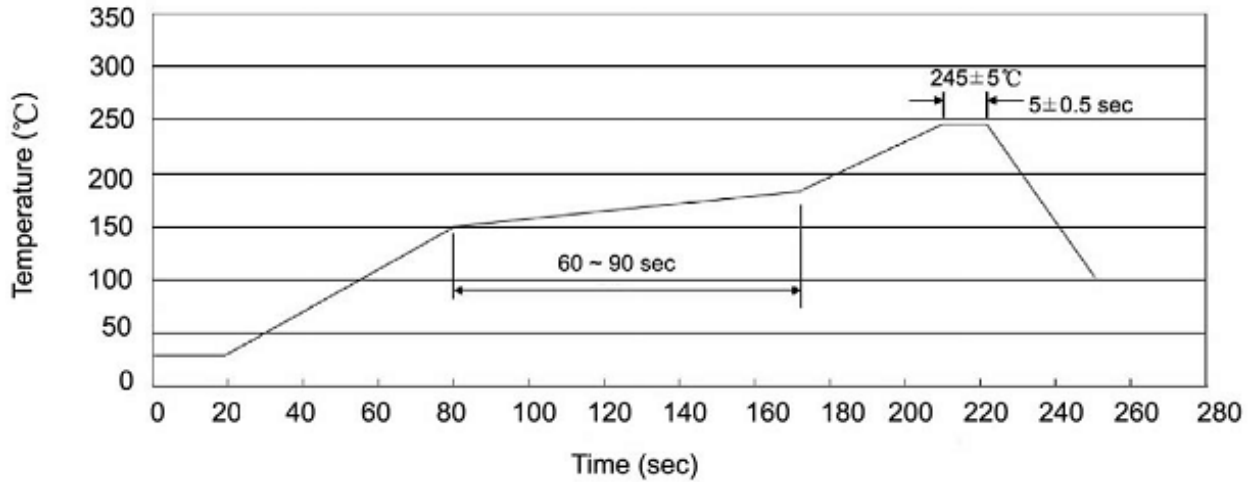
说明：

D 为型号代码

Note:

D Product Type.

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec；
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec；
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-323	3,000	10	30,000	6	180,000	7" x8	180×120×180	390×385×205

**使用说明 / Notices**